

MATERIALS AND FINISHES

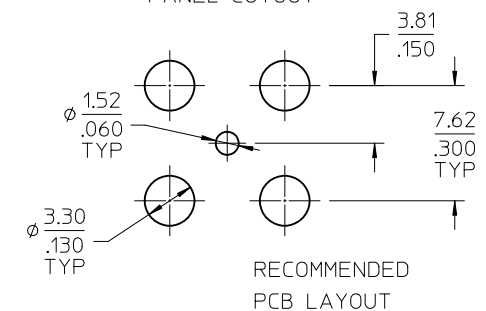
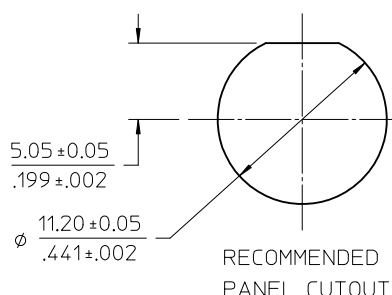
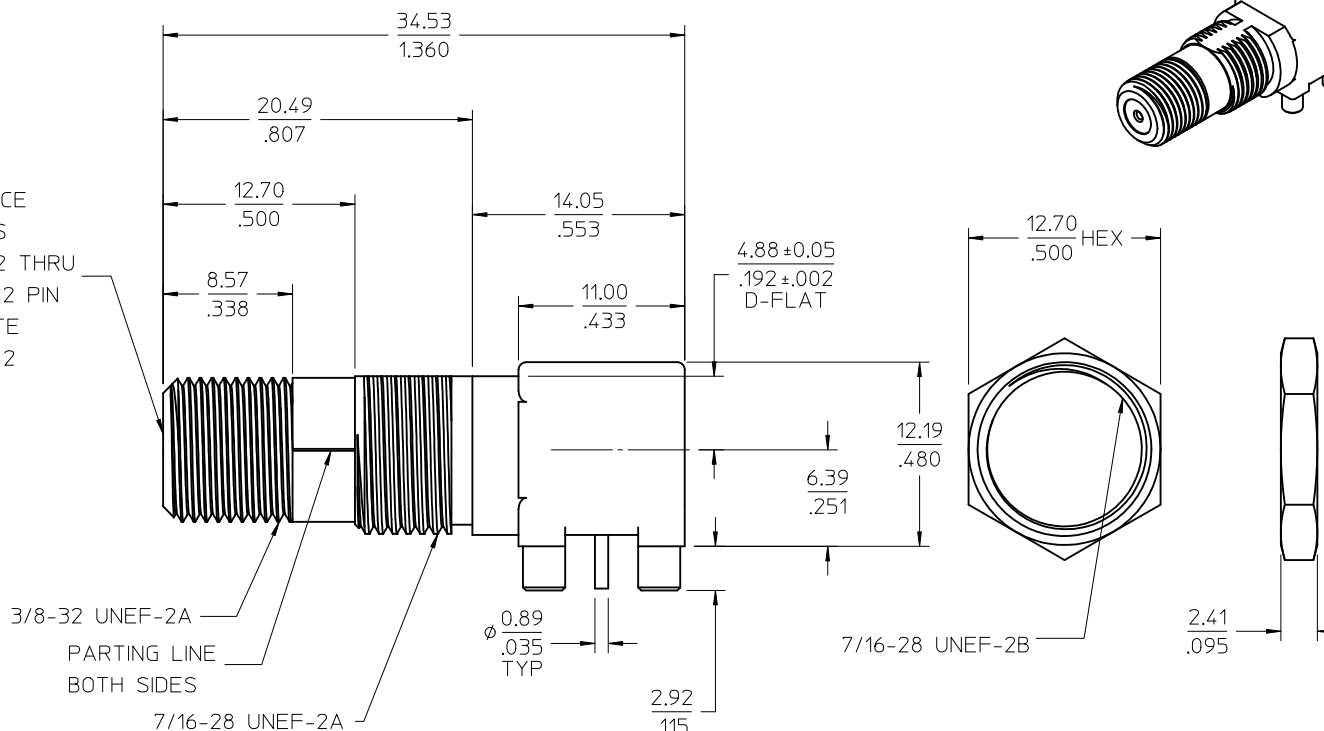
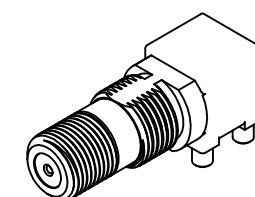
BODY: ZINC ALLOY
 PLATED TIN (100 MICROINCHES MIN)
 OVER NICKEL (50 MICROINCHES MIN)
 OVER COPPER (320 MICROINCHES MIN)

CENTER CONTACT: PHOSPHOROUS BRONZE
 BRASS/BERYLLIUM COPPER
 PLATED TIN (150 MICROINCHES MIN)
 OVER NICKEL (100 MICROINCHES MIN)
 FEMALE SPRING PLATED GOLD

INSULATOR: TEFLON

JAM NUT: BRASS
 PLATED NICKEL (100 MICROINCHES MIN)

F JACK
 INTERFACE ACCEPTS
 $\phi .56/.022$ THRU
 $\phi 1.07/1.042$ PIN
 SEE NOTE
 4 PAGE 2



73356-0402	WITH JAM NUT
73356-0401	WITHOUT JAM NUT
73356-0400	WITH JAM NUT
PART NO.	DESCRIPTION

RoHS
 COMPLIANT

CHG: ADD NOTE 4 ON PAGE TWO EC NO: URF2010-0347 DRWN: WIENER 2009/12/28 CHKD: SSHAH 2009/12/28 APPR: WIENER 2009/12/28 REV: 5	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± .010</td> <td>± .0004</td> </tr> <tr> <td>3 PLACES</td> <td>± .015</td> <td>± .0006</td> </tr> <tr> <td>2 PLACES</td> <td>± .020</td> <td>± .0008</td> </tr> <tr> <td>1 PLACE</td> <td>± .030</td> <td>± .0012</td> </tr> </table> ANGULAR ± 2 °		mm	INCH	4 PLACES	± .010	± .0004	3 PLACES	± .015	± .0006	2 PLACES	± .020	± .0008	1 PLACE	± .030	± .0012	DIMENSION STYLE MM/IN	SCALE DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																	
	4 PLACES	± .010	± .0004																	
	3 PLACES	± .015	± .0006																	
2 PLACES	± .020	± .0008																		
1 PLACE	± .030	± .0012																		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY SSS 2005/05/31	CHECKED BY TEF 2005/05/31	APPROVED BY JDW 2005/05/31	TITLE F JACK, R/A, PCB 75 OHMS, HIGH PERF F-J/RA/PCB EWR2813	MOLEX INCORPORATED															
MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-73356-040	SHEET NO. 1 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	

PRODUCT SPECIFICATION NOTES:

MEETS IPS SP 400 R09 WITH FOLLOWING EXCEPTIONS.

1. DIMENSION J CHAMFER NOT PRESENT.
2. NOTE 6 (WILL HAVE STANDARD DIECAST FINISH).
3. NOTE 4 (WILL HAVE PARTING LINES).
4. MATING INTERFACE WILL MAINTAIN ELECTRICAL CONTACT WITH $\phi 0.56$ ($\phi.022$) SIZE PIN AFTER 20 MATING CYCLES WITH $\phi 1.07$ ($\phi.042$) SIZE PIN

ELECTRICAL PERFORMANCE

RETURN LOSS: 26 dB MAX 5-2000 MHZ
 INSERTION LOSS: .1 dB MAX TO 2000 MHZ
 IMPEDANCE: 75 OHM
 CURRENT: 1 AMP WITHOUT DAMAGE
 CONTACT TEMPERATURE RISE: 15°C @ 1 AMP CONTINUOUS
 EXTERNAL CONTACT RESISTANCE: 1 mOHM MAX
 CENTER CONTACT RESISTANCE: 2 mOHM MAX
 INSULATION RESISTANCE: 1000 MOHM MIN
 VOLTAGE RATING: 500 Vrms 50/60 Hz
 DIELECTRIC WITHSTANDING VOLTAGE: 1500 Vrms (LEAKAGE CURRENT 500 μ AMP MAX)

CHG: SEE SHEET 1. EC NO: URF2010-0347 DRWN: JWIENER 2009/12/28 CHKD: SSHAH 2009/12/28 APPR: JWIENER 2009/12/28	DESCRIPTION REV C5	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
		=0 =0	mm	INCH	MM/IN			METRIC				
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± --- ± ---	1 PLACE ± --- ± ---	DRAWN BY	DATE	TITLE				
		ANGULAR ± 2 °				SSS	2005/05/31	F JACK, R/A, PCB 75 OHMS, HIGH PERF F-J/RA/PCB EWR2813				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE TABLE		MOLEX INCORPORATED		DOCUMENT NO.		SHEET NO.		
				MATERIAL NO.		SD-73356-040		2 OF 2				
				SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						